# RICHTEK®

## 120m $\Omega$ , 1.8A Power Switch with Adjustable Current Limit

#### **General Description**

The RT9728B is a cost effective, low voltage, single P-MOSFET power switch IC for USB application with a adjustable current limit feature. Low switch-on resistance (typ. 120m $\Omega$ ) and low supply current (typ. 120µA) are realized in this IC. The RT9728B can offer a adjustable current limit threshold between 75mA and 1.8A (typ.) via an external resistor. The ±10% current limit accuracy can be realized for all current limit settings. In addition, a flag output is available to indicate fault conditions to the local USB controller. Furthermore, the chip also integrates an embedded delay function to prevent mis-operation due to high inrush current. The RT9728B is an ideal solution for USB power supplies and can support flexible applications since it is suitable for various current limit requirements. It is available in the SOT-23-6 and WDFN-6L 2x2 packages.

### Applications

- USB Bus/Self Powered Hubs
- USB Peripheral Ports
- ACPI Power Distribution
- Battery Power Equipment
- 3G/3.5G Data Card, Set-Top Boxes

#### **Features**

- ±10% Current Limit Accuracy @ 1.3A
- Adjustable Current Limit : 75mA to 1.8A (typ.)
- Meets USB Current Limiting Requirements
- Operating Voltage Range : 2.5V to 5.5V
- Reverse Input–Output Voltage Protection
- Built-in Soft-Start
- 120mΩ P-MOSFET
- 120µA Supply Current
- RoHS Compliant and Halogen Free

### **Ordering Information**

#### RT9728B

Package Type E : SOT-23-6 QW : WDFN-6L 2x2 Lead Plating System G : Green (Halogen Free and Pb Free)

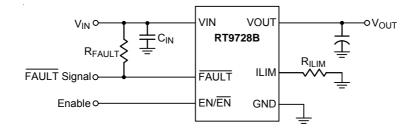
H : Chip Enable High
 L : Chip Enable Low

Note :

Richtek products are :

- RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- Suitable for use in SnPb or Pb-free soldering processes.

#### **Simplified Application Circuit**





### **Marking Information**

RT9728BHGE

0K=DNN	

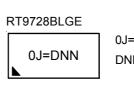
RT9728BHGQW

1RW

0K= : Product Code DNN : Date Code

1R : Product Code

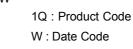
W : Date Code



0J= : Product Code DNN : Date Code

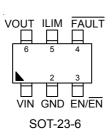
#### RT9728BLGQW

1QW



## Ð

### **Pin Configuration**



**Functional Pin Description** 

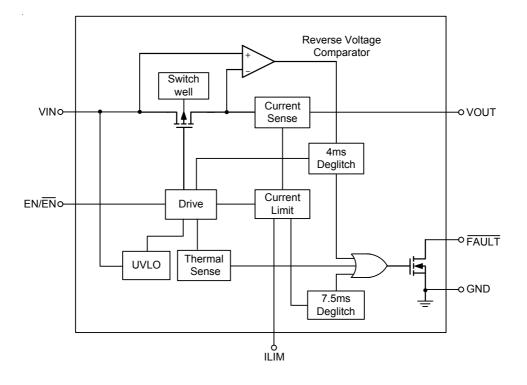
(TOP VIEW)

ILIM	2)	GND		
FAULT	3		4	EN/EN

WDFN-6L 2x2

I dilotion								
Pin No. SOT-23-6 WDFN-6L 2x2		Pin Name	Pin Function					
1	6	VIN	Power input.					
2	5, 7 (Exposed Pad)	GND	Ground. The exposed pad must be soldered to a large PCB and connected to GND for maximum power dissipation.					
3	4	EN/EN	Enable control input.					
4	3	FAULT	Active-low open-drain output. Asserted during over-current, over-temperature, or reverse-voltage conditions.					
5	2	ILIM	$\begin{array}{l} \mbox{Current limit setting. Connect an external resistor to set current} \\ \mbox{limit threshold. } 15 k\Omega \leq R_{ILIM} \leq 232 k\Omega \mbox{ is recommended.} \end{array}$					
6	1	VOUT	Power switch output.					

#### **Functional Block Diagram**



### Operation

The RT9728B is a current-limited power switch using P-MOSFET for applications where short-circuit or heavy capacitive loads will be encountered. These devices allow users to adjust the current limit threshold between 75mA and 1.8A (typ.) via an external resistor. Additional device shutdown features include over-temperature protection and reverse-voltage protection.

The RT9728B provides built-in soft-start function. The driver controls the gate voltage of the power switch. The driver incorporates circuitry that controls the rising time and falling time of the output voltage to limit large inrush current and voltage surges. The RT9728B enters constant-current mode when the load exceeds the current limit threshold.



### Absolute Maximum Ratings (Note 1)

Supply Input Voltage, VIN	
• Other Pins	0.3V to 6V
<ul> <li>Power Dissipation, P<sub>D</sub> @ T<sub>A</sub> = 25°C</li> </ul>	
SOT-23-6	0.4W
WDFN-6L 2x2	0.606W
Package Thermal Resistance (Note 2)	
SOT-23-6, θ <sub>JA</sub>	250°C/W
WDFN-6L 2x2, θ <sub>JA</sub>	165°C/W
WDFN-6L 2x2, θ <sub>JC</sub>	7°C/W
Lead Temperature (Soldering, 10 sec.)	260°C
Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
ESD Susceptibility (Note 3)	
HBM (Human Body Model)	2kV

### Recommended Operating Conditions (Note 4)

Supply Input Voltage, VIN	- 2.5V to 5.5V
Junction Temperature Range	40°C to 125°C
Ambient Temperature Range	40°C to 85°C

### **Electrical Characteristics**

(	$V_{IN} = 3.6V.$	$15k\Omega \leq R_{ILIM}$	$\leq 232 k \Omega$ .	T₄ = 25°C.	unless	otherwise	specified)
<u>۱</u>	, • IIN 0.0 •,		,		41110000	011011100	opoomoa,

Parameter		Symbol	Test Cond	litions	Min	Тур	Max	Unit
Logic-High		Vih			1.1			V
EN Input Voltage	Logic-Low	VIL					0.66	V
Current Limit Thre Resistor Range	shold	RILIM	(nominal 1%) from ILIN	/I to GND	15		232	kΩ
Under-Voltage Loc	kout	Mana	V <sub>IN</sub> rising			2.3	1	V
Threshold		Vuvlo	V <sub>IN</sub> falling			2.1		v
Shutdown Current		I <sub>SHDN</sub>	$V_{IN}$ = 3.6V, no load on $V_{OUT}$ , $V_{EN}$ = 0V			1	3	μA
Quiescent Current		$I_Q$ $V_{IN} = 5.5V,$ no load on $V_{OUT}$	V <sub>IN</sub> = 5.5V,	$R_{ILIM}$ = 20k $\Omega$		120	170	μA
			no load on V <sub>OUT</sub>	$R_{ILIM}$ = 210k $\Omega$		120	170	
Reverse Leakage	Current	I <sub>REV</sub>	V <sub>OUT</sub> = 5V, V <sub>IN</sub> = 0V			1	10	μA
Thermal Shutdowr	n Threshold	T <sub>SD</sub>				160		°C
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	I <sub>SW</sub> = 0.2A			120		mΩ
Current Limit			$R_{\rm ILIM} = 20 k\Omega$ $R_{\rm ILIM} = 49.9 k\Omega$		1166	1295	1425	
		1			468	520	572	
		ILIM	R <sub>ILIM</sub> = 210kΩ		104	130	156	mA
			ILIM shorted to VIN			75		

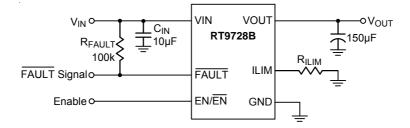


Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Reverse Voltage Comparator Trip Point ( $V_{OUT} - V_{IN}$ )				135		mV
FAULT Output Low Voltage	Vol	IFAULT = 1mA		180		mV
FAULT Off State Leakage		VFAULT = 5.5V		1		μA
FAULT Deglitch		FAULT assertion or de-assertion due to over-current condition	5	7.5	10	
		FAULT assertion or de-assertion due to reverse-voltage condition	2	4	6	ms

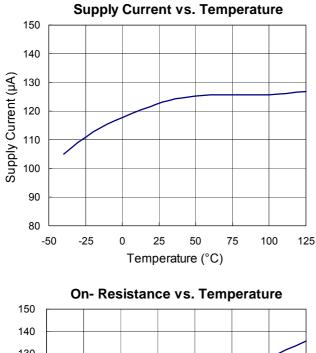
- **Note 1.** Stresses beyond those listed "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- **Note 2.**  $\theta_{JA}$  is measured at  $T_A = 25^{\circ}C$  on a low effective thermal conductivity single-layer test board per JEDEC 51-3.  $\theta_{JC}$  is measured at the exposed pad of the package.
- Note 3. Devices are ESD sensitive. Handling precaution is recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.

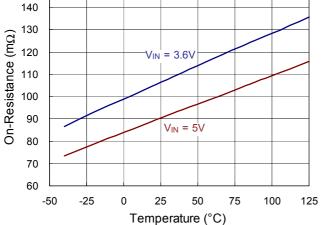


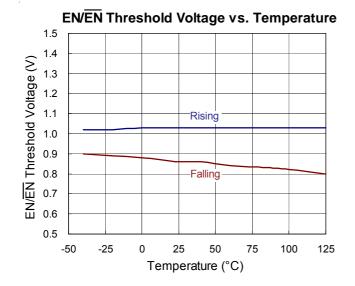
## **Typical Application Circuit**

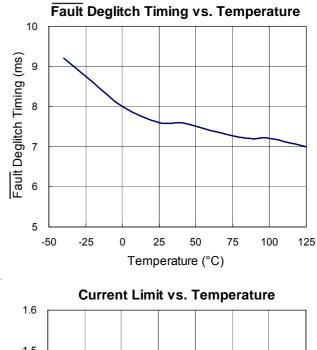


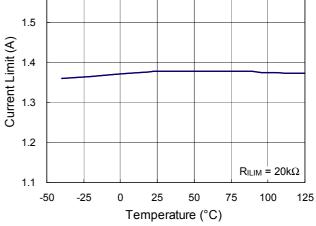
### **Typical Operating Characteristics**



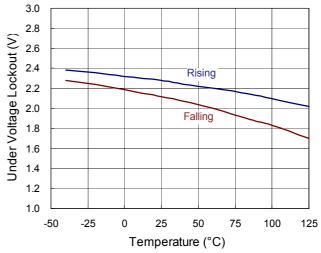




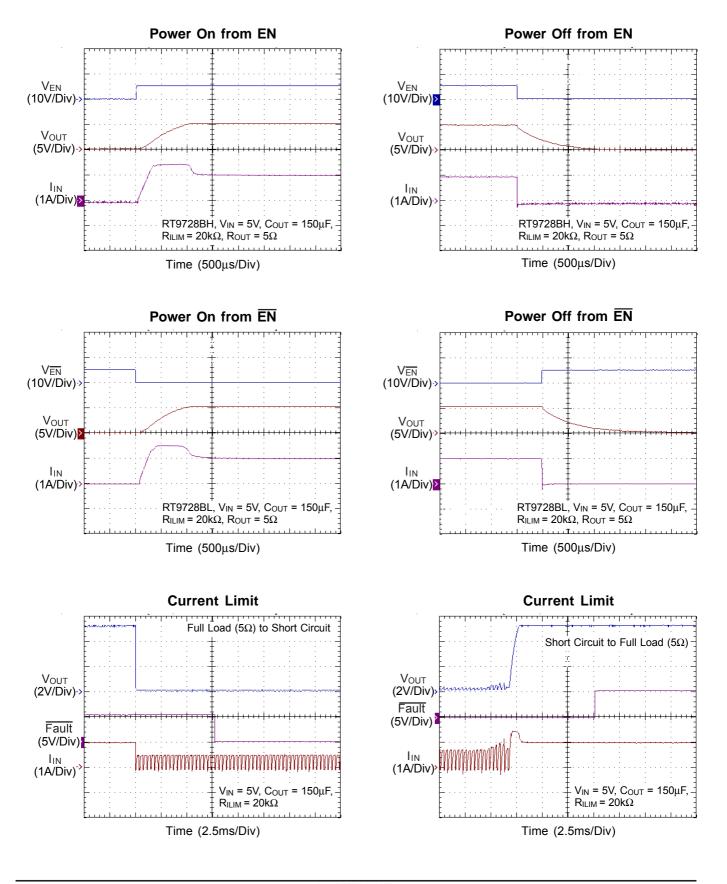




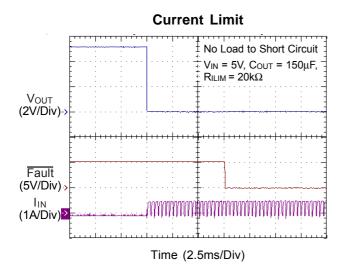
Under Voltage Lockout vs. Temperature

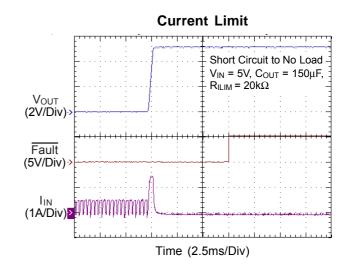


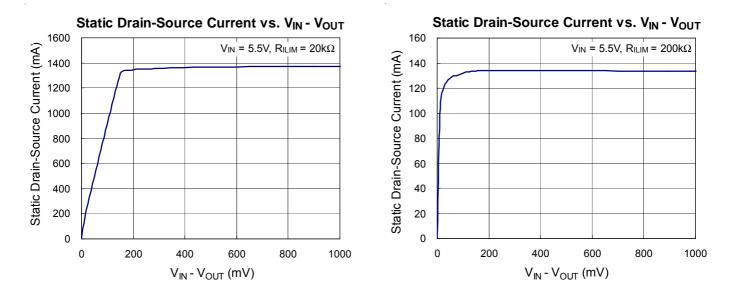
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#### **Applications Information**

The RT9728B is a single P-MOSFET power switch with an active-high/low enable input, optimized for self-powered and bus-powered Universal Serial Bus (USB) applications. The switch's low  $R_{DS(ON)}$  meets USB voltage drop requirements and a flag output is available to indicate fault conditions to the local USB controller.

#### **Current Limit and Short-Circuit Protection**

When a heavy load or short-circuit situation occurs while the switch is enabled, a large transient current may flow through the device. The RT9728B includes current-limit circuitry to prevent the MOSFET switch and the hub downstream ports from damage due to large transient current. The RT9728B provides an adjustable current limit threshold between 120mA and 1.8A (typ) via an external resistor, R<sub>ILIM</sub>, whose resistance is between 15k $\Omega$  and 232k $\Omega$ . However, if the ILIM pin is connected to V<sub>IN</sub>, the current limit threshold will be 75mA (typ). Once the current limit threshold is exceeded, the device enters constantcurrent mode until either thermal shutdown occurs or the fault is removed. Figure 1 shows the curve of current limit value vs.  $R_{ILIM}$  resistor. The recommended  $R_{ILIM}$  resistor selection is shown in Table 1.

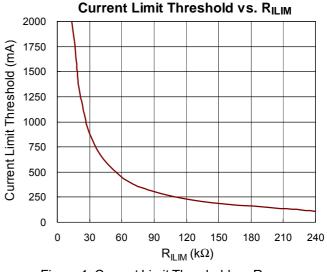


Figure 1. Current Limit Threshold vs. RILIM

Desired Nominal	Ideal Resistor	Closet 1%	Actual L	imits (Include R To	olerance)
Current Limit (mA)	<b>(k</b> Ω)	Resistor (k $\Omega$ )	IOS Min (mA)	IOS Nom (mA)	IOS Max (mA)
75	Short ILI	M to VIN	50.0	75.0	100.0
120	226.1	226.0	101.3	120.0	142.1
200	134.0	133.0	173.7	201.5	233.9
300	88.5	88.7	262.1	299.4	342.3
400	65.9	66.5	351.1	396.7	448.7
500	52.5	52.3	443.9	501.6	562.4
600	43.5	43.2	535.1	604.6	674.1
700	37.2	37.4	616.0	696.0	776.0
800	32.4	32.4	708.7	800.8	892.9
900	28.7	28.7	797.8	901.5	1005.2
1000	25.8	26.1	875.4	989.1	1102.8
1100	23.4	23.2	982.1	1109.7	1237.3
1200	21.4	21.5	1057.9	1195.4	1332.9
1300	19.7	19.6	1158.0	1308.5	1459.0
1400	18.5	18.7	1225.7	1385.0	1544.3
1500	17.3	17.4	1317.3	1488.5	1659.7
1600	16.2	16.2	1414.8	1598.7	1782.6
1700	15.2	15.0	1528.1	1726.7	1925.3
1800	14.4	14.3	1602.9	1811.2	2019.5

#### Table 1. Recommended RILIM Resistor Selection

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DS9728B-02 September 2019

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#### Fault Flag

The RT9728B provides a FAULT signal pin which is an open-drain N-MOSFET output. This open-drain output is pulled low when current exceeds current limit threshold. The FAULT output is capable of sinking a 1mA load to 180mV (typ.) above ground. The FAULT pin requires a pull-up resistor; this resistor should be large in value to reduce energy drain. A 100k $\Omega$  pull-up resistor works well for most applications. In case of an over-current condition, FAULT will be asserted only after the flag response delay time,  $t_{\text{D}},$  has elapsed. This ensures that FAULT is asserted upon valid over-current conditions and that erroneous error reporting is eliminated. For example, false over-current conditions may occur during hot-plug events when extremely large capacitive loads are connected, which induces a high transient inrush current that exceeds the current limit threshold. The FAULT response delay time, t<sub>D</sub>, is typically 7.5ms.

#### Supply Filter/Bypass Capacitor

A 10 $\mu$ F low ESR ceramic capacitor connected from V<sub>IN</sub> to GND and located close to the device is strongly recommended to prevent input voltage drooping during hotplug events. However, higher capacitor values may be used to further reduce the voltage droop on the input. Without this bypass capacitor, an output short may cause sufficient ringing on the input (from source lead inductance) to destroy the internal control circuitry. Note that the input transient voltage must never exceed 6V as stated in the Absolute Maximum Ratings.

#### **Output Filter Capacitor**

A low ESR 150 $\mu$ F aluminum electrolytic capacitor connected between V<sub>OUT</sub> and GND is strongly recommended to meet the USB standard maximum droop requirement for the hub, VBUS. Standard bypass methods should be used to minimize inductance and resistance between the bypass capacitor and the downstream connector to reduce EMI and decouple voltage droop caused by hot-insertion transients in downstream cables. Ferrite beads in series with VBUS, the ground line and the 0.1 $\mu$ F bypass capacitors at the power connector pins are recommended for EMI and ESD protection. The bypass capacitor itself should have a low dissipation factor to allow decoupling at higher frequencies.

#### Chip Enable Input

The RT9728BH/L is disabled when the EN/EN pin is in a logic-low/high condition. During this condition, the internal circuitry and MOSFET are turned off, reducing the supply current to 1 $\mu$ A typically. The maximum guaranteed voltage for a logic-low at the EN/EN pin is 0.66V. A minimum guaranteed voltage of 1.1V at the EN/EN pin will turn off the RT9728B. Floating the input may cause unpredictable operation. EN/EN should not be allowed to go negative with respect to GND.

#### **Under-Voltage Lockout**

Under-Voltage Lockout (UVLO) prevents the MOSFET switch from turning on until input voltage exceeds approximately 2.3V. If input voltage drops below approximately 2.1V, UVLO turns off the MOSFET switch.

#### **Thermal Considerations**

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

#### $\mathsf{P}_{\mathsf{D}(\mathsf{MAX})} = (\mathsf{T}_{\mathsf{J}(\mathsf{MAX})} - \mathsf{T}_{\mathsf{A}}) \ / \ \theta_{\mathsf{JA}}$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance,  $\theta_{JA}$ , is layout dependent. For SOT-23-6 packages, the thermal resistance,  $\theta_{JA}$ , is 250°C/W on a standard JEDEC 51-3 single-layer thermal test board. For WDFN-6L 2x2 packages, the thermal resistance,  $\theta_{JA}$ , is 165°C/W on a standard JEDEC 51-3 single-layer thermal test board. The maximum power



dissipation at  $T_A$  = 25°C can be calculated by the following formula :

 $P_{D(MAX)}$  = (125°C - 25°C) / (250°C/W) = 0.400W for SOT-23-6 package

 $P_{D(MAX)}$  = (125°C - 25°C) / (165°C/W) = 0.606W for WDFN-6L 2x2 package

The maximum power dissipation depends on the operating ambient temperature for fixed  $T_{J(MAX)}$  and thermal resistance,  $\theta_{JA}$ . The derating curves in Figure 2 allow the designer to see the effect of rising ambient temperature on the maximum power dissipation.

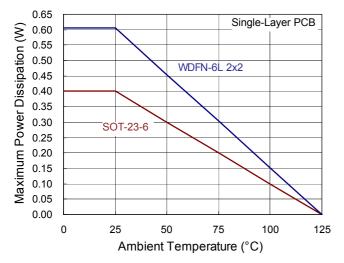
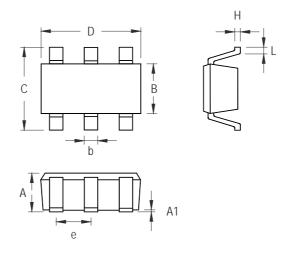


Figure 2. Derating Curve of Maximum Power Dissipation



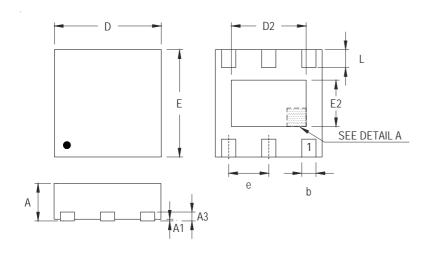
## **Outline Dimension**

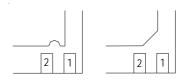


Symbol	Dimensions	n Millimeters	Dimension	s In Inches
Symbol	Min	Max	Min	Max
А	0.889	1.295	0.031	0.051
A1	0.000	0.152	0.000	0.006
В	1.397	1.803	0.055	0.071
b	0.250	0.560	0.010	0.022
С	2.591	2.997	0.102	0.118
D	2.692	3.099	0.106	0.122
е	0.838	1.041	0.033	0.041
Н	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024

SOT-23-6 Surface Mount Package







DETAIL A Pin #1 ID and Tie Bar Mark Options

Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min	Max	Min	Max
А	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.175	0.250	0.007	0.010
b	0.200	0.350	0.008	0.014
D	1.950	2.050	0.077	0.081
D2	1.000	1.450	0.039	0.057
E	1.950	2.050	0.077	0.081
E2	0.500	0.850	0.020	0.033
е	0.650		0.0	)26
L	0.300	0.400	0.012	0.016

W-Type 6L DFN 2x2 Package

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